

Description

The AP40N02D uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a

Battery protection or in other Switching application.



 $V_{DS} = 20V I_{D} = 40 A$

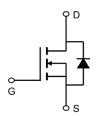
 $R_{DS(ON)}$ < 10m Ω @ V_{GS} =10V

Application

Battery protection

Load switch

Uninterruptible power supply







Package Marking and Ordering Information

Product ID Pack		Marking	Qty(PCS)	
AP40N02D	TO-252-3L	AP40N02D XXXX YYYY	2500	

Absolute Maximum Ratings (T_C=25°Cunless otherwise noted)

Symbol	Parameter	Limit	Unit
V _{DS}	Drain-Source Voltage	20	V
Vgs	Gate-Source Voltage	±12	V
I _D	Drain Current-Continuous	40	Α
I _D (100℃)	Drain Current-Continuous(T _C =100℃)	28	Α
Івм	Pulsed Drain Current	80	Α
P _D	Maximum Power Dissipation	40	W
Eas	Single pulse avalanche energy (Note 5)	150	mJ
Тл,Тѕтс	Operating Junction and Storage Temperature Range	-55 To 150	°C
Reuc	Thermal Resistance,Junction-to-Case ^(Note 2)	3.8	°CMV



Electrical Characteristics (T_A=25 ℃ unless otherwise noted)

Symbol	Parameter	Condition		Тур	Max	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V I _D =250µA	20	-	-	V
IDSS	Zero Gate Voltage Drain Current	V _{DS} =20V,V _{GS} =0V	-	-	1	μΑ
Igss	Gate-Body Leakage Current	V _{GS} =±12V,V _{DS} =0V	-	-	±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} ,I _D =250µA	0.5	0.7	1.2	V
RDS(ON)	Drain-Source On-State Resistance	V _{GS} =4.5V, I _D =25A	-	6.2	10	mΩ
RDS(ON)	Drain-Source On-State Resistance	V _{GS} =2.5V, I _D =10A	-	9.1	12	mΩ
grs	Forward Transconductance	V _{DS} =5V,I _D =20A	10	-	-	S
Clss	Input Capacitance			1100		PF
Coss	Output Capacitance			162		PF
Crss	Reverse Transfer Capacitance	F=1.0MHz		105		PF
td(on)	Turn-on Delay Time		-	4.5	-	nS
t _r	Turn-on Rise Time	VGS=10V,VDS=10V	-	9.2	-	nS
td(off)	Turn-Off Delay Time	RL=0. 5Ω,RGEN=3Ω	-	18.7	-	nS
t _f	Turn-Off Fall Time		-	3.3	-	nS
Qg	Total Gate Charge			15		nC
Qgs	Gate-Source Charge	VGS=10V,VDS=10V,ID=20A		1.8		nC
Q _{gd}	Gate-Drain Charge			2.8		nC
Vsp	Diode Forward Voltage (Note 3)	V _{GS} =0V,I _S =20A	-	-	1.2	V
Is	Diode Forward Current (Note 2)	-	-	-	30	Α
t _{rr}	Reverse Recovery Time	TJ = 25°C, IF = 20A di/dt =	-	18	-	nS
Qrr	Reverse Recovery Charge	100A/µs ^(Note3)	-	9.5	-	nC
ton	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

Notes:

- 1、Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2、Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3、Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production
- 5 EAS condition: Tj=25°C,V_{DD}=10V,V_G=10V,L=0.5mH,Rg=25 Ω



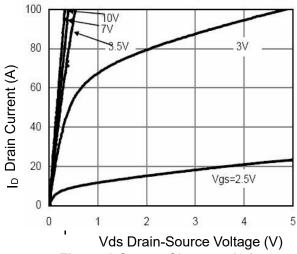
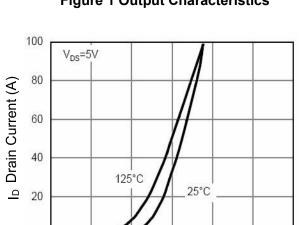


Figure 1 Output Characteristics



Vgs Gate-Source Voltage (V) **Figure 2 Transfer Characteristics**

1.5

2

2.5

3

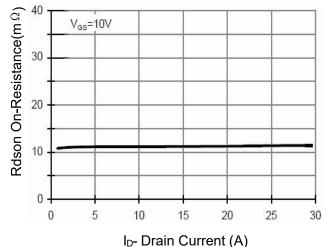
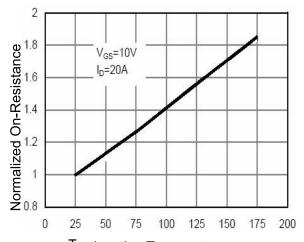
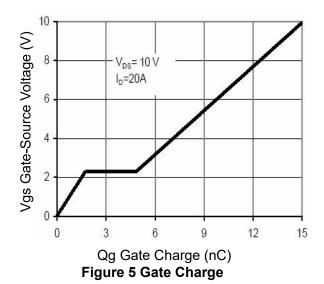


Figure 3 RdsonDrain Current





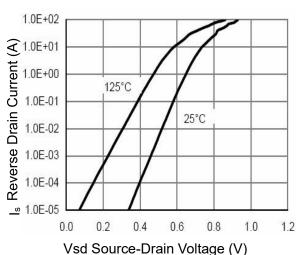


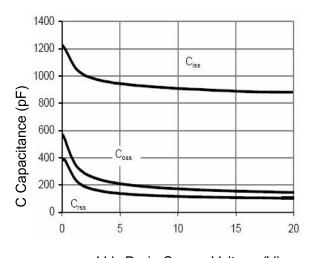
Figure 6 Source- Drain Diode Forward



0 0

0.5

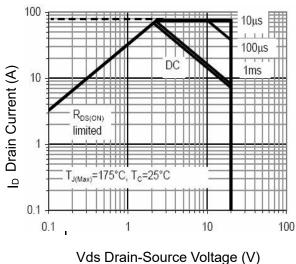




Power Dissipation (W)

Vds Drain-Source Voltage (V) Figure 7 Capacitance vs Vds

T_J-Junction Temperature($^{\circ}$ C) Figure 9 Power De-rating



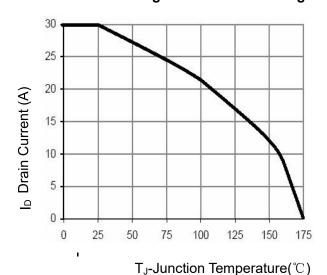


Figure 8 Safe Operation Area

Figure 10 Current De-rating

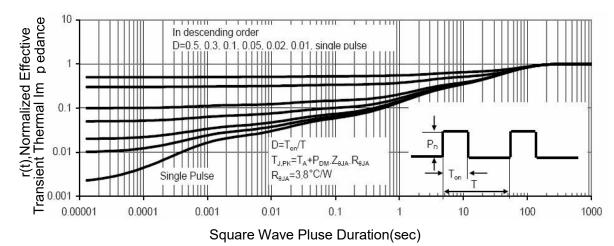
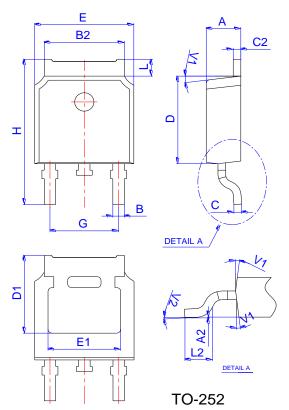


Figure 11 Normalized Maximum Transient Thermal Impedance

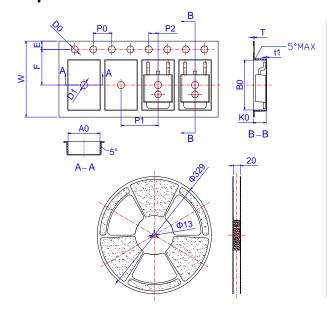


Package Mechanical Data:TO-252-3L



	Dimensions					
Ref.	Millimeters			Inches		
	Min.	Тур.	Max.	Min.	Тур.	Max.
Α	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
В	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
С	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
Н	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

Reel Spectification-TO-252



	Dimensions					
Ref.	Millimeters			Inches		
	Min.	Тур.	Max.	Min.	Тур.	Max.
W	15.90	16.00	16.10	0.626	0.630	0.634
Е	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
D0	1.40	1.50	1.60	0.055	0.059	0.063
D1	1.40	1.50	1.60	0.055	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
A0	6.85	6.90	7.00	0.270	0.271	0.276
В0	10.45	10.50	10.60	0.411	0.413	0.417
K0	2.68	2.78	2.88	0.105	0.109	0.113
Т	0.24		0.27	0.009		0.011
t1	0.10			0.004		
10P0	39.80	40.00	40.20	1.567	1.575	1.583



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AP40N02D

20V N-Channel Enhancement Mode MOSFET

Edition	Date	Change
Rve3.2	2018/8/31	Initial release
Rve3.3	2019/11/31	Reduce RDS

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Test Report For 30PCS (30pcs 典型測試報告)

